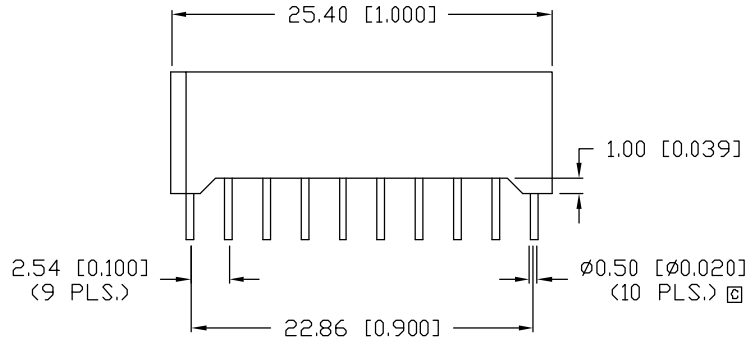
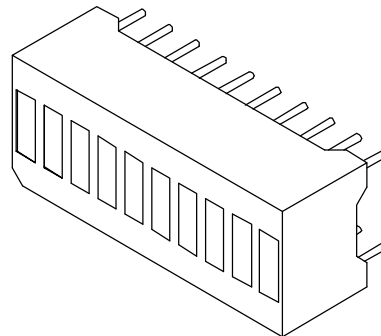
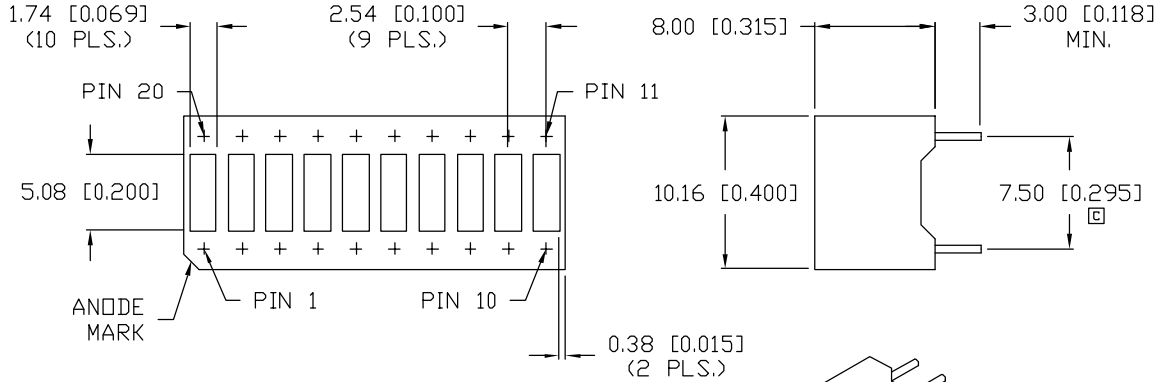
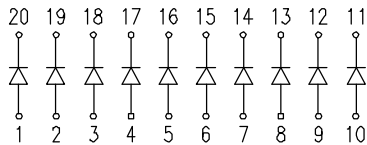


UNCONTROLLED DOCUMENT



TOP VIEW POLARITY



PART NUMBER  
SSA-LXB10IW

REV.  
D

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	CHG'D SAVE OPER SPECS.	6.7.94
B	CHG'D SAVE OPER SPECS.	8.29.94
C	E.C.N. #10477. & #10BRDR. & REDRAWN.	5.12.99
D	E.C.N. #10BRDR. & REDRAWN.	7.2.01

ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635		nm	
FORWARD VOLTAGE		2.0	2.5	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_r=100\mu\text{A}$
AXIAL INTENSITY		8		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		160		$2x$ theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	MILKY WHITE DIFFUSED				
FACE COLOR:	BLACK				

ⓂⓂ LIMITS OF SAFE OPERATION AT  $25^\circ\text{C}$  PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM $25^\circ\text{C}$	-1.2	$\text{mW}/^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

\*  $t < 10\mu\text{s}$

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION MAX= +0.00 -DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV.	PART NUMBER SSA-LXB10IW
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10 SEGMENT RECTANGULAR BAR GRAPH,  
RED CHIPS, MILKY WHITE DIFFUSED.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT	CHECKED BY:	APPROVED BY:	DATE: 10.14.93 PAGE: 1 OF 1 SCALE: D
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